

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (currently amended) An IC card comprising:

a semiconductor device having a semiconductor chip at least partially sealed with a first sealing portion made of a thermosetting resin material and having, over a first surface, an external connection terminal electrically connected to the semiconductor chip;

a case which is made of a thermoplastic resin material and ~~upon~~ which the semiconductor device is ~~to be~~ loaded; and

a second sealing portion which is made of a thermoplastic resin material bonded to said case and sealing~~and seals~~ the semiconductor device so as to expose the external connection terminal, thereby integrating the semiconductor device with the case.

2. (currently amended) An IC card according to Claim 1,

wherein the semiconductor device further comprises a wiring substrate providing~~having~~ the first surface over which the external connection terminal is formed and an interconnect~~+~~, wherein the semiconductor chip is disposed

over the wiring substrate and electrically connected to the external connection terminal via the interconnect; ~~and the first sealing portion made of a thermosetting resin material and formed over the wiring substrate so as to seal the semiconductor chip at least partially.~~

3. (previously presented) An IC card according to Claim 2, wherein the first sealing portion is formed to cover the semiconductor chip.

4. (previously presented) An IC card according to Claim 2, wherein the semiconductor device has a connecting member for electrically connecting the interconnect of the wiring substrate with the semiconductor chip, and the first sealing portion covers the connecting member.

5. (currently amended) An IC card according to Claim 2, wherein the semiconductor chip is disposed over a surface of the wiring substrate on a side opposite to at the first ~~surface over which the external connection terminal is~~ formed.

6. (previously presented) An IC card according to Claim 1, wherein the second sealing portion is formed to cover a region, other than the external connection terminal, of the first surface of the semiconductor device.

7. (previously presented) An IC card according to Claim 1, wherein the case and the second sealing portion are made of the same material.

8. (currently amended) An IC card according to Claim 1, wherein the second sealing portion is welded ~~with the~~ to an interface portion of the case.

9. (currently amended) An IC card according to Claim 1, wherein ~~a projecting portion is formed over the first surface of the semiconductor device~~ has a projecting portion, the external connection terminal is formed over the projecting portion of the first surface, and the second sealing portion is formed to cover a region, other than the projecting portion, of the first surface ~~of the semiconductor device~~.

10. (previously presented) An IC card according to Claim 1, wherein the first sealing portion is made of an epoxy resin containing a silica filler.

11. (currently amended) An IC card according to Claim 1,  
wherein the semiconductor device further comprises:

a die pad portion, the semiconductor chip being  
disposed over the die pad portion; and

a lead portion electrically connected to the  
semiconductor chip; and

wherein the first sealing portion ~~cover~~sing the die  
pad portion, the semiconductor chip and the lead portion and  
~~expos~~ing, as the external connection terminal, a part of  
the lead portion from ~~an~~the outer surface of the first  
sealing portion.

Claims 12-24 (canceled)

25. (new) The IC card of claim 1, wherein the second  
sealing portion has a portion molded to the case.

26. (new) The IC card of claim 2, wherein the second  
sealing portion has a portion molded to the wiring  
substrate.

27. (new) The IC card of claim 2, wherein the second  
sealing portion has a first portion bonded to the case and a  
second portion bonded to the wiring substrate.

28. (new) The IC card of claim 27, wherein said first and second portions of the second sealing portion are unitary with each other.

29. (new) The IC card of 28, wherein said second portion of the second sealing portion is bonded to the first surface of the wiring substrate.

30. (new) The IC card of claim 28, wherein said second portion of the second sealing portion is bonded to a peripheral edge of the wiring substrate.

31. (new) The IC card of claim 2, wherein the second sealing portion has a portion molded to the first surface of the wiring substrate and a portion molded to a peripheral edge of the wiring substrate.